

REMARKS

Claims 66 and 67 were pending in the present application. New claims 68 -70 are added herein. Thus claims 66-70 are now pending in the present application. Reconsideration of the present application in view of the above amendments and the following remarks is respectfully requested.

Applicants note that acknowledgement of the claim for priority made under section 119 and notice that all certified copies of the priority documents have been received was not provided. It should be noted that the claim for priority was perfected in parent U.S. Application Serial No. 09/717,227 and thus, since PTOL-326 provides for acknowledgement of receipt of priority documents in a parent case, e.g. Item 12. (a)-(c). 2. of PTOL-326, and since the present application is a continuation thereof, applicants hereby request that the examiner provide acknowledgment of receipt of priority documents by way of the parent application (Ser. No 09/717,227).

Applicants also note the receipt of an initialed copy of form PTO-1449 including 4 pages thereof associated with the Information Disclosure Statement filed on November 4, 2003, on which the examiner has indicated consideration by initialing all listed items.

Claims 66 and 67 stand rejected under 35 U.S.C. §102(b) as being allegedly anticipated by Lee, U.S. Patent No. 4,620,215. Claim 66 is amended herein to address this ground of rejection.

With regard to claim 66, as amended, a novel feature is recited including, inter alia, the claimed bump is formed of resin and securely bonds the control terminal to the semiconductor chip. The use of resin in the claimed invention is an improvement over the metal bonding pads

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of Lee in that the low modulus of elasticity of resin improves durability of the bump as compared to prior art bonding methods.

In stark contrast, Lee describes a packaging system where a bonding pad (73) secures a chip (70) to beam leads (85). Bonding pad (73) includes metal layers (73A) around the bonding pad (73), for example, as shown in FIG. 3 of Lee. The encapsulating material (86) has a low modulus of elasticity in comparison to with the modulus of elasticity of the chip (70) the substrate (60) and the heat sink (80). Therefore, large stresses can occur in the system of Lee which can break the bonding pad (73) when both ends of beam leads (85) are held.

Accordingly a *prima facie* case of anticipation has not been established in that the applied reference fails to disclose all the claimed features as required. It is respectfully requested therefore that the rejection of claim 66 be reconsidered and withdrawn.

Claim 67 by virtue of depending from claim 66, is believed allowable for at least the reasons set forth hereinabove with regard to claim 66. It is respectfully requested that the rejection of claim 67 be reconsidered and withdrawn.

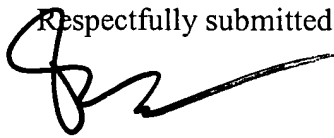
New claims 68 -70 recite features, including conductive members protruding from the radiation members, associated with the present embodiment as further described in applicants specification, for example, on page 25, line 23 to page 26 line 3. New claims 68 -70 further recite that the bump is formed of a resin and forms a secure bond between the control terminal and the semiconductor chip. Favorable consideration is requested.

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In view of the foregoing, the applicants respectfully submit that this application is in condition for allowance and a timely notice to that effect is respectfully requested. If questions relating to patentability remain, the examiner is invited to contact the undersigned by telephone.

Please charge any unforeseen fees that may be due to Deposit Account No. 50-1147.

Respectfully submitted,



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